



VMDSEMI

VFTA010R080NA

Datasheet



VMDSEMI

General Description

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
100V	8mΩ@10V	95A
	10mΩ@10V	

Symbol

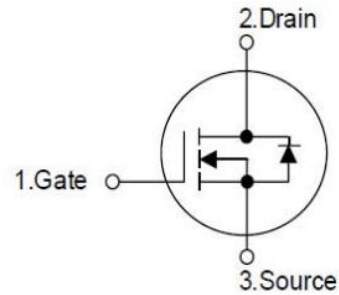


Figure 1 Symbol of VFTA010R080NA

Features

- $R_{DS(ON)_{max}} = 8.0m\Omega @ V_{GS} = 10V$
- Extremely low switching loss
- Excellent stability and uniformity EMI Improved
- Fast switching and soft recovery

Application

- BMS
- Switched mode power supply
- E-tools
- Server/Telecom

Package Type

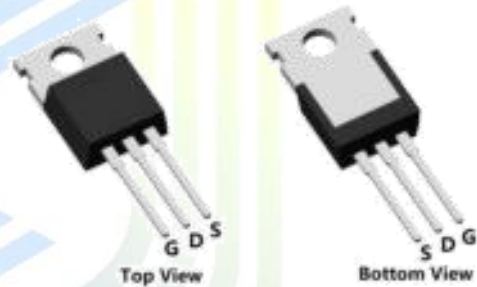


Figure 2 Package Type of VFTA010R080NA

Ordering Information

Product Name	Package
VFTA010R080NA	TO-220

Absolute Maximum Ratings

Parameter		Symbol	Rating	Unit
Drain-Source Voltage		V_{DSS}	100	V
Gate-Source Voltage		V_{GSS}	±20	V
Continuous Drain Current ^{Note1}	$T_C=25^{\circ}\text{C}$	I_D	95	A
	$T_C=100^{\circ}\text{C}$		59	
Pulsed Drain Current ^{Note2}	$T_C=25^{\circ}\text{C}$	I_{DM}	282	A
Max Power Dissipation ^{Note3}	$T_C=25^{\circ}\text{C}$	P_D	90	W
Avalanche Current, Single Pulse ^{Note4}		I_{AS}	33.5	A
Avalanche Energy, Single Pulse ^{Note4}		E_{AS}	281	mJ
Continuous Diode Forward Current	$T_C=25^{\circ}\text{C}$	I_S	94	A
Operation and storage temperature		T_J, T_{STG}	-55 to 150	$^{\circ}\text{C}$

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Case ^{Note4}	$R_{\theta JC}$		1.4		$^{\circ}\text{C}/\text{W}$
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$		60		

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature $T_{J(MAX)}=150^{\circ}\text{C}$.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) P_D is based on max. junction temperature, using junction-case thermal resistance.
- 4) EAS test condition: $V_{DS}=25\text{V}$, $V_{GS}=10\text{V}$, $L=0.5\text{mH}$, $R_G=25\Omega$, Starting $T_J=25^{\circ}\text{C}$

Electrical Characteristics ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=100V, V_{GS}=0V$			1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu A$	1.2	1.65	2.4	V
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=30A$		5.8	8	mΩ
		$V_{GS}=4.5V, I_D=20A$		7.4	10	
Dynamic Characteristics						
Input Capacitance	C_{ISS}	$V_{DS}=20V$		1880		pF
Output Capacitance	C_{OSS}	$V_{GS}=0V$		1299		pF
Reverse Transfer Capacitance	C_{RSS}	$f=1MHz$		113		pF
Gate Resistance	R_G	$f=1MHz$		0.65		Ω
Total Gate Charge (@ $V_{GS}=4.5V$)	Q_g	$V_{DS}=50V,$ $I_D=30A$		16.9		nC
Total Gate Charge (@ $V_{GS}=10V$)	Q_g			32.8		
Gate to Source Charge	Q_{gs}			5.7		
Gate to Drain Charge	Q_{gd}			8.0		
Switching Characteristics						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=50V,$ $V_{GS}=10V,$ $I_D=30A,$ $R_G=3\Omega$		6.5		ns
Rise Time	t_r			4.8		
Turn-off Delay Time	$t_{d(off)}$			22.7		
Fall Time	t_f			7.0		
Reverse Diode Characteristics						
Drain-Source Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_D=30A$		0.87	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=50V,$		26		ns
Reverse Recovery Charge	Q_{rr}	$I_F=30A,$		21		nC
Peak Reverse Recovery Current	I_{rrm}	$di/dt=100A/\mu s$		1.6		A

Typical Performance Characteristics

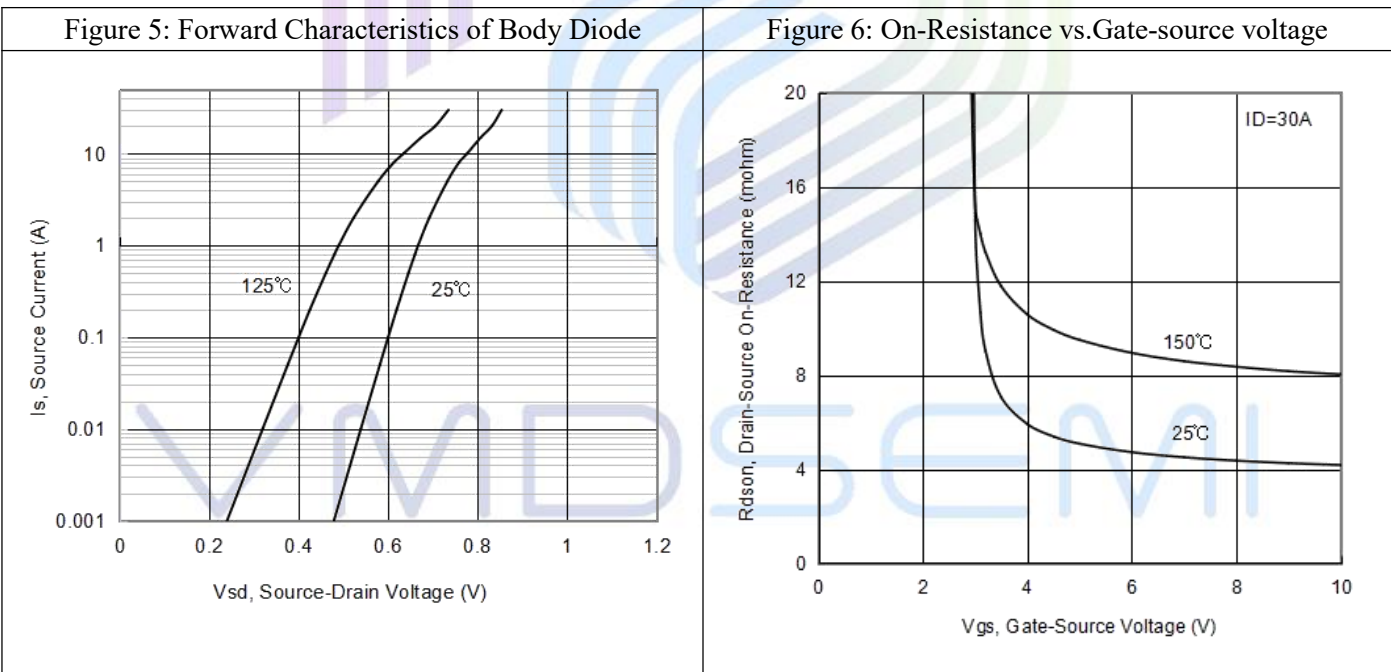
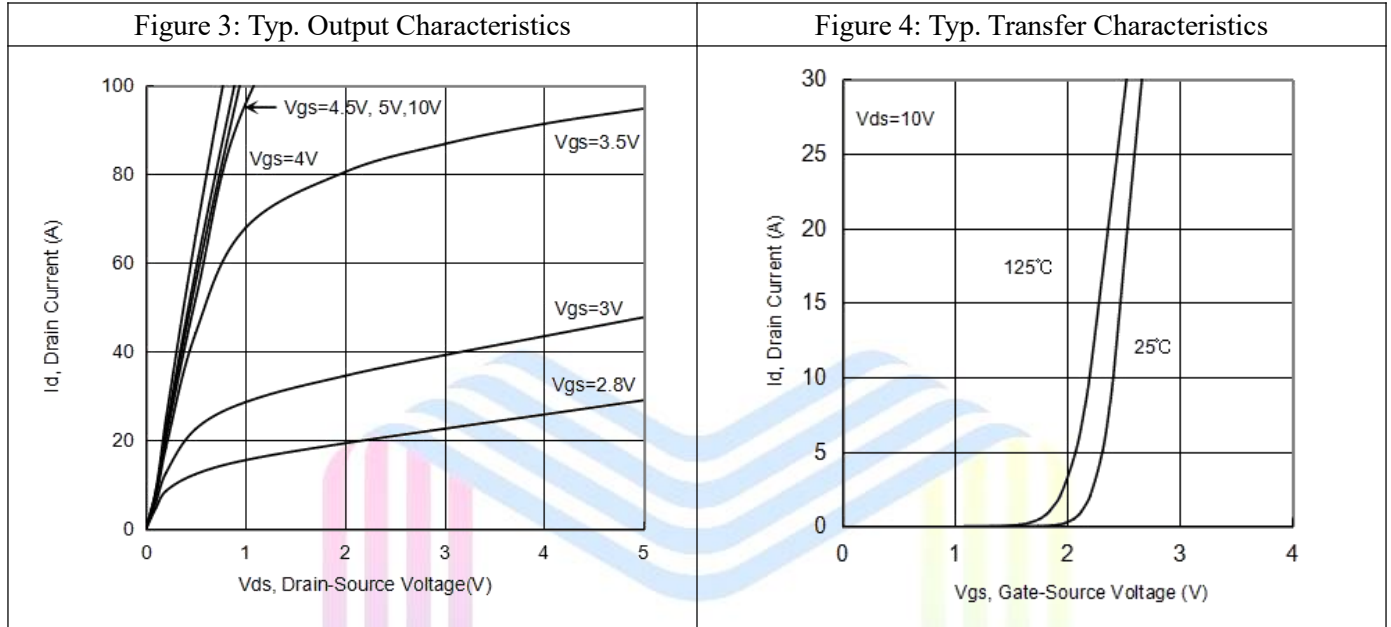


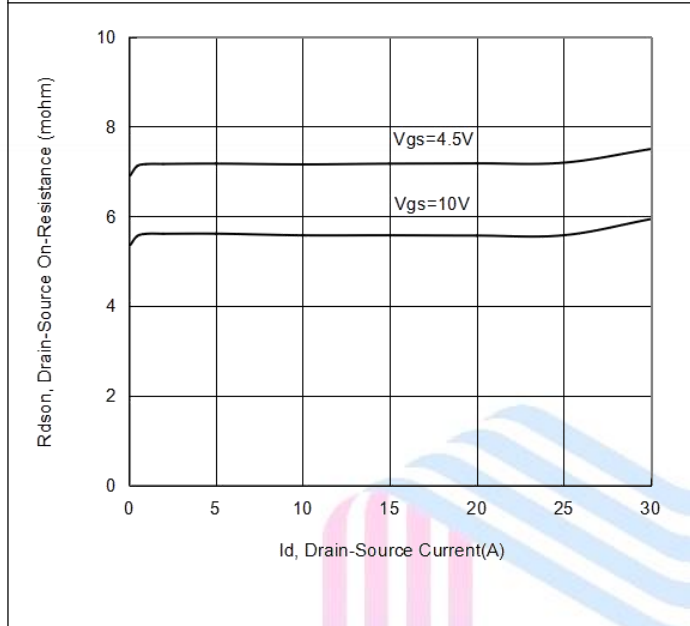
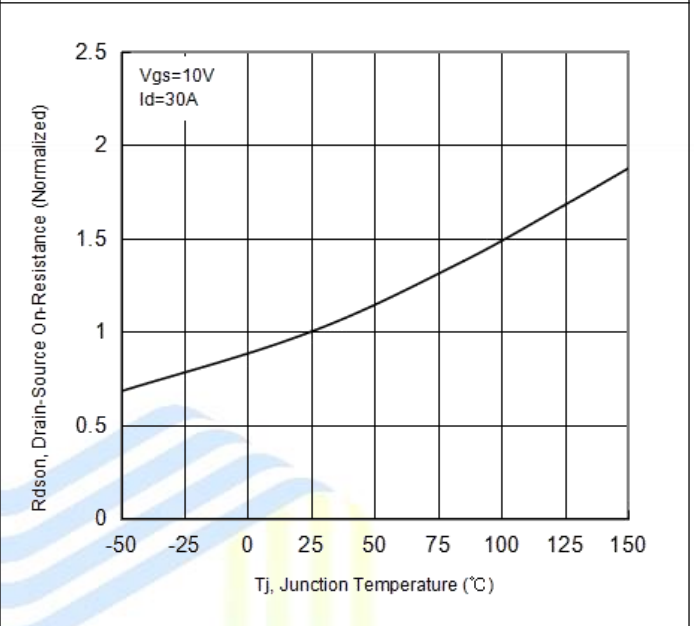
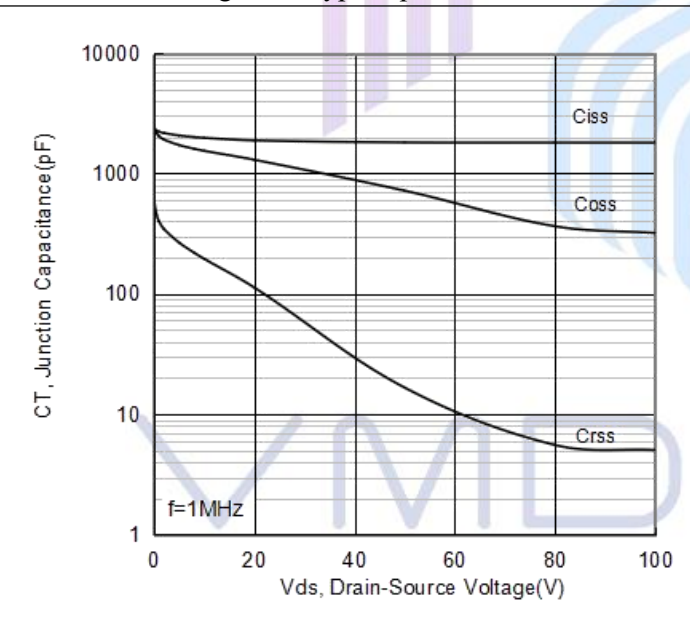
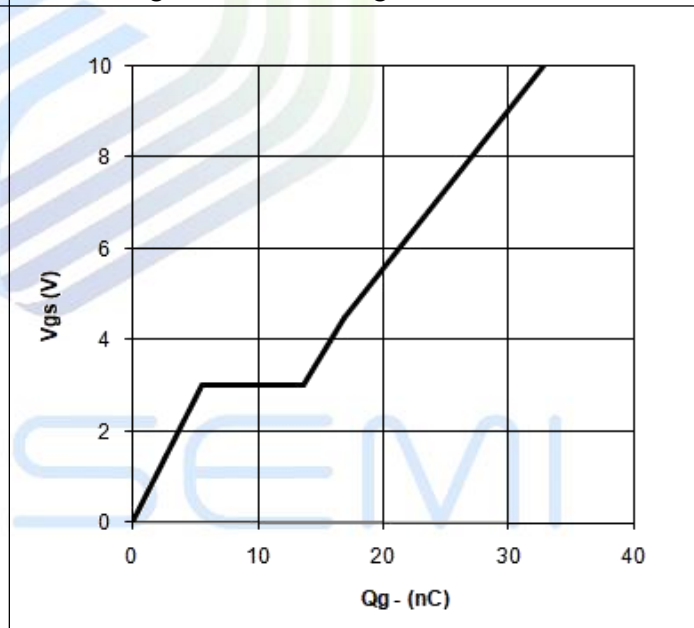
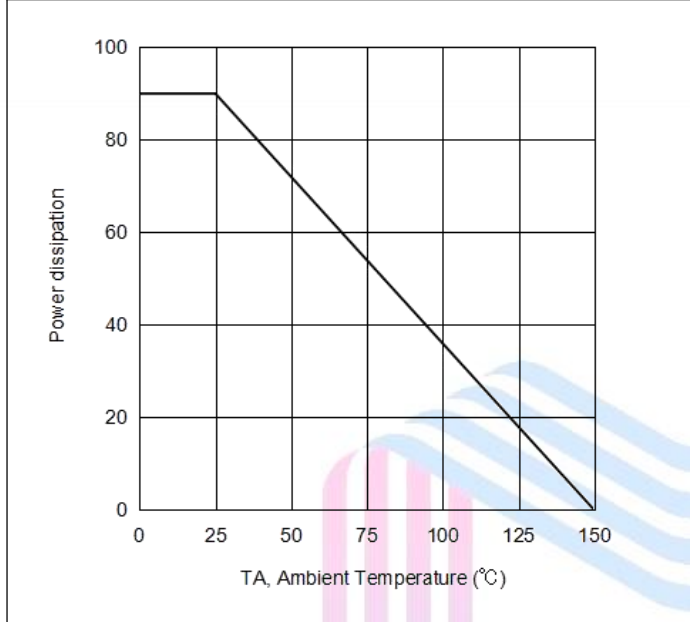
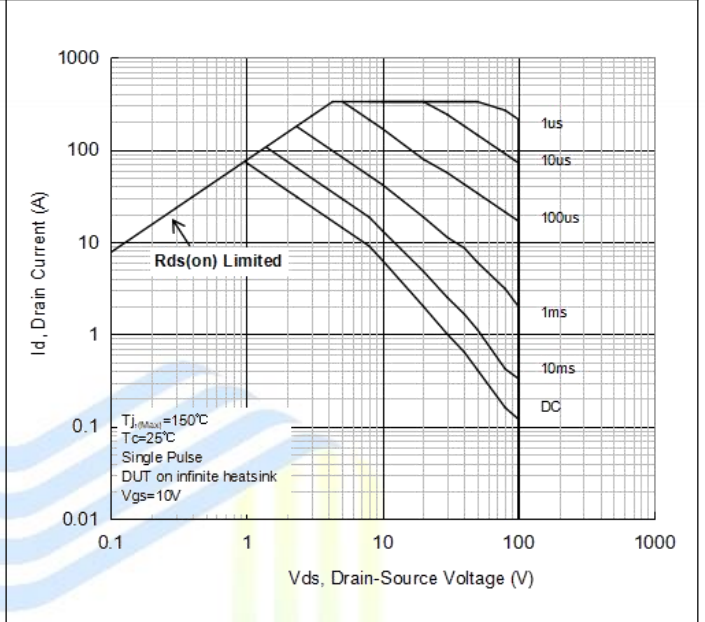
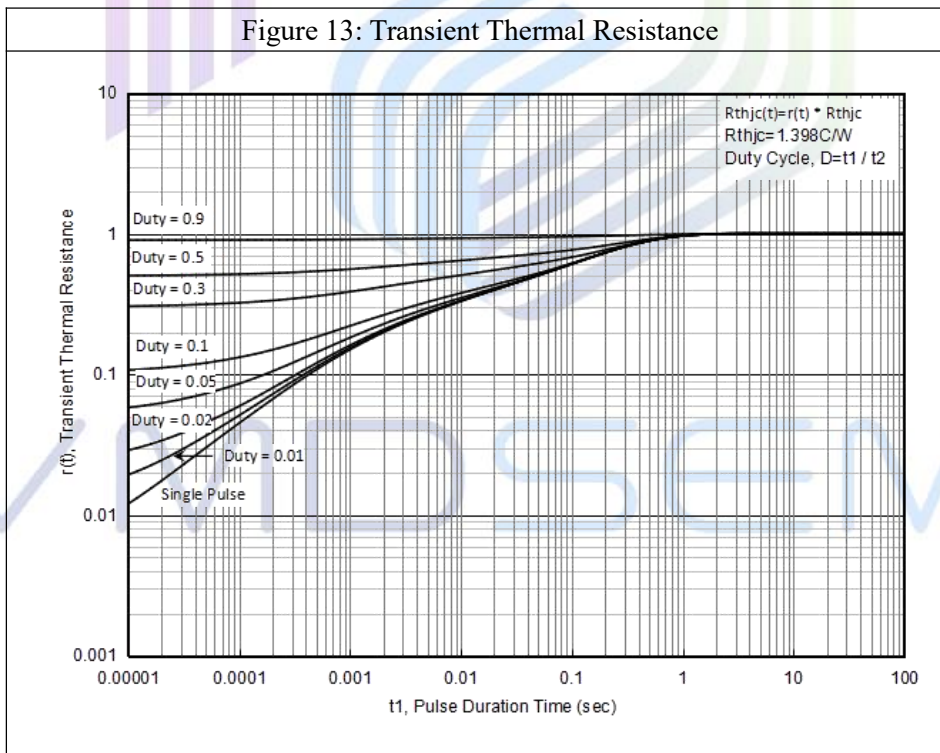
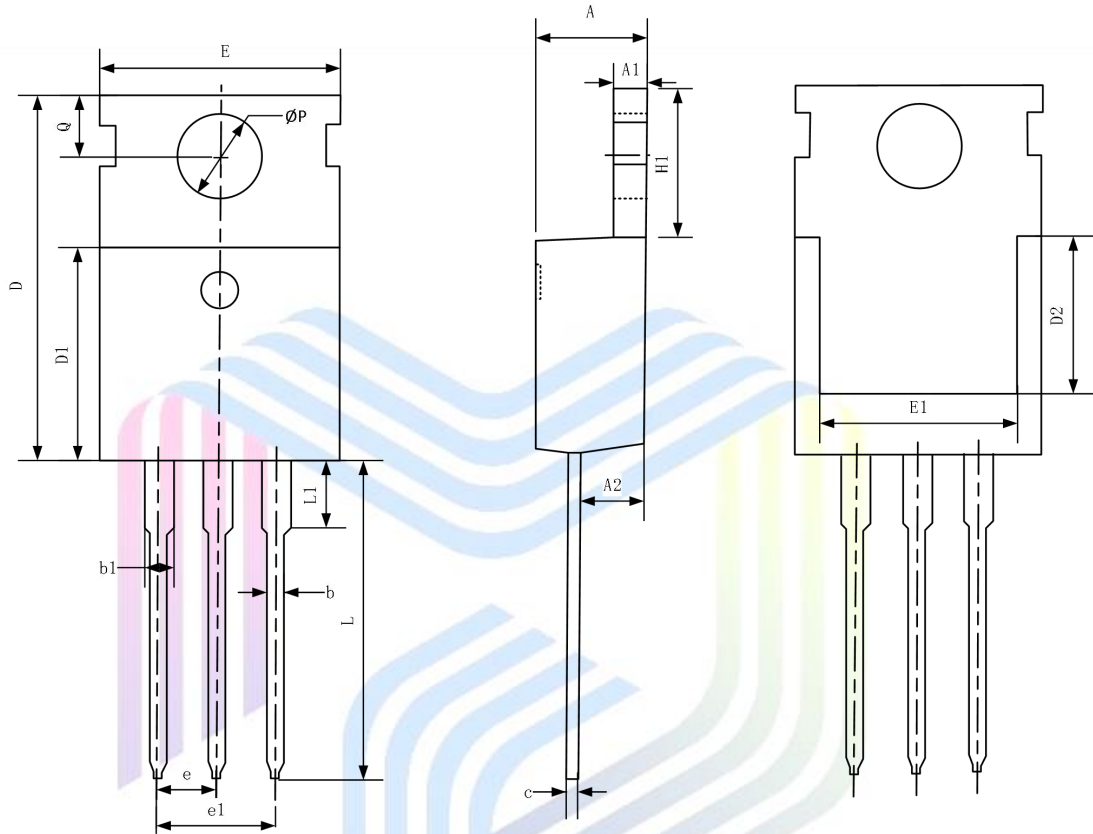
Figure 7: Drain-Source On-State Resistance

Figure 8: Normalized R_{ds(on)} vs Temperature

Figure 9: Typ. Capacitance

Figure 10: Gate Charge Characteristics


Figure11: Power Dissipation

Figure12: Safe Operating Area

Figure 13: Transient Thermal Resistance


Mechanical Dimensions

TO220 Package Information



SYMBOL	MILLIMETER	
	MIN	MAX
A	4.37	4.70
A1	1.25	1.40
A2	2.20	2.60
b	0.70	0.95
b1	1.17	1.47
c	0.45	0.60
D	15.10	16.10
D1	8.80	9.40
D2	5.50	-
E	9.70	10.30
E1	7.00	-
e	2.54 BSC	
e1	5.08 BSC	
H1	6.25	6.85
L	12.75	13.80
L1	-	3.40
ØP	3.40	3.80
Q	2.60	3.00

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